COMPLIANT

HALOGEN FREE

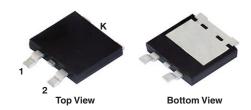


Vishay General Semiconductor

Dual High-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low $V_F = 0.49 \text{ V}$ at $I_F = 5.0 \text{ A}$

eSMP[®] Series SMPD (TO-263AC)





DESIGN SUPPORT TOOLS AVAILABLE



PRIMARY CHARACTERISTICS				
I _{F(AV)}	2 x 15 A			
V _{RRM}	100 V			
I _{FSM}	160 A			
V _F at I _F = 15 A (T _A = 125 °C)	0.66 V			
T _J max.	175 °C			
Package	SMPD (TO-263AC)			
Circuit configuration	Common cathode			

FEATURES

- Trench MOS Schottky technology
- Very low profile typical height of 1.7 mm
- · Ideal for automated placement
- · Low forward voltage drop, low power losses
- · High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

MECHANICAL DATA

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)					
PARAMETER		SYMBOL	V30DM100C	UNIT	
Device marking code			V30DM100C		
Maximum repetitive peak reverse voltage		V _{RRM}	100	V	
Maximum average forward rectified current (fig. 1)	per device	I _{F(AV)} ⁽¹⁾	30	Α	
	per diode		15	A	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load		I _{FSM}	160	А	
Operating junction temperature range		T _J ⁽²⁾	-40 to +175	- °C	
Storage temperature range		T _{STG}	-55 to +175		

Notes

- (1) Mounted on infinite heatsink
- $^{(2)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta,JA}$



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I _F = 5 A	T _A = 25 °C	- V _F ⁽¹⁾	0.55	-	. V
	I _F = 7.5 A			0.61	-	
	I _F = 15 A			0.76	0.81	
	I _F = 5 A	T _A = 125 °C		0.49	-	
	I _F = 7.5 A			0.54	-	
	I _F = 15 A			0.66	0.74	
Reverse current at rated V _R per diode	V _R = 70 V	T _A = 25 °C	I _R ⁽²⁾	0.01	-	mA
		T _A = 125 °C		2.5	-	
	V _R = 100 V	T _A = 25 °C		-	0.4	
		T _A = 125 °C		5	14	
Typical junction capacitance	4.0 V, 1 MHz		CJ	1300	-	pF

Notes

 $^{(1)}$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width $\leq 5 \text{ ms}$

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V30DM100C	UNIT	
Typical thermal resistance per device	R ₀ JC ⁽¹⁾	1.6	°C/W	
	R ₀ JA (2)(3)	58] 5/44	

Notes

- (1) Mounted on infinite heatsink
- $^{(2)} \ \, \text{The heat generated must be less than the thermal conductivity from junction-to-ambient:} \ dP_D/dT_J < 1/R_{\theta JA} \text{ junction-to-ambient}$
- (3) Free air, without heatsink

ORDERING INFORMATION (Example)						
PREFERRED P/N	P/N UNIT WEIGHT (g) PACKAGE CODE		BASE QUANTITY	DELIVERY MODE		
V30DM100C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel		
V30DM100CHM3/I (1)	0.55	I	2000/reel	13" diameter plastic tape and reel		

Note

(1) AEC-Q101 qualified

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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

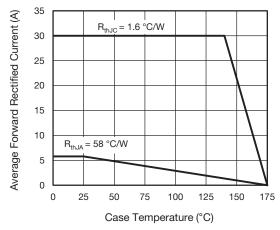


Fig. 1 - Maximum Forward Current Derating Curve

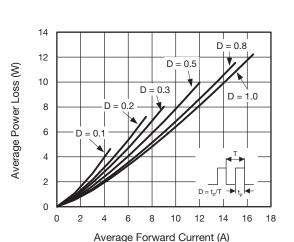


Fig. 2 - Average Power Loss Characteristics

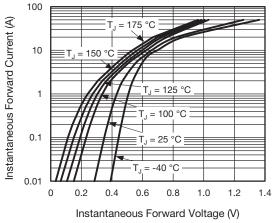


Fig. 3 - Typical Instantaneous Forward Characteristics

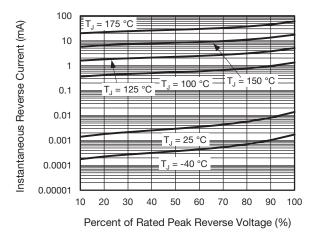


Fig. 4 - Typical Reverse Leakage Characteristics

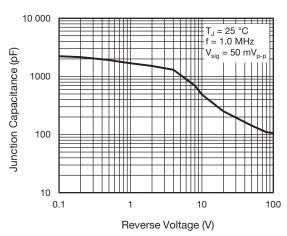


Fig. 5 - Typical Junction Capacitance

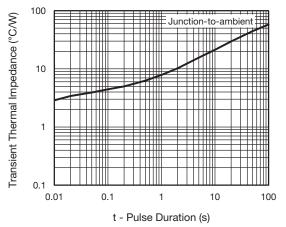


Fig. 6 - Typical Transient Thermal Impedance



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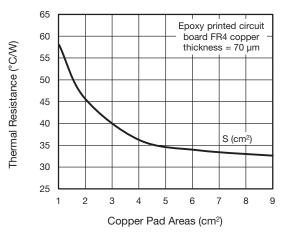
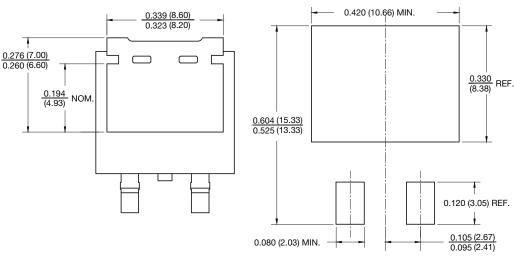


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD (TO-263AC) 0.402 (10.20) 0.386 (9.80) 0.071 (1.80) 0.063 (1.60) 0.020 (0.52) 0.011 (0.27) -0.059 (1.50) REF. 0.048 (1.21) 0.354 (8.99) 0.338 (8.59) 0.509 (12.93) 0.485 (12.33) 0 to 0.01 (0 to 0.254) 0.069 (1.74) 0.053 (1.34) 0.063 (1.60) 0.020 (0.52) 0.047 (1.20) 0.011 (0.27) 0.052 (1.23) 0.028 (0.72) Mounting Pad Layout 0.420 (10.66) MIN. 0.339 (8.60)





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